



MATERIAL DATA FORM

Manufacturer contact information

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Manufacturer's Part Number	Total Mass of the Unit specified in (g)	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
DMP3056LSS	0.075	Die,Switch	Doped silicon	TBD	0.8395	1.12%	11170
Customer's Partnumber		SOIC-8 leadframe	CDA-194	37507841	39.0286	51.93%	519335
			Die attached pad plating	37507916	0.7140	0.95%	9501
		Bonding wire	Copper	TBD	0.3678	0.49%	4894
		Molding compound	EME-G700	TBD	32.1639	42.80%	427990
		Die attach epoxy	84-1 LMISR4	TBD	0.3378	0.45%	4495
		Tin solder	Pure Tin	37508652	1.6994	2.26%	22614
Total (mg)					75.151		



**MATERIAL DATA FORM DETAIL**

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight	Additional Information (e.g. complete polymeric Material Trade Name or metallic Material Standard). Please declare "No FR" when the polymeric material	Manufacturer Part & Version No.	Date of completion. dd/mm/yyyy	Dummy No.	Customer Project.	Diodes ECN No.	Manufacturer DUNS Number			
DMP3056LSS	0.075	Die,Switch	Doped silicon	Si	7440-21-3	0.8395	100.00%	1000000	11170										
Customer's Partnumber.		SOIC-8 leadframe	CDA 194	Cu	7440-50-8	38.0139	97.40%	974000	505833										
				Fe	1309-37-1	0.9367	2.40%	24000	12464										
				P	7723-14-0	0.0312	0.08%	800	415										
				Zn	7440-66-6	0.0468	0.12%	1200	623										
				Pure silver	Ag	7440-22-4	0.7140	100.00%	1000000	9501									
				Bonding wire	2.0 mil	Cu	7440-50-8	0.3678	100.00%	1000000	4894								
				Molding compound	EME-G700	Epoxy Resin	-----	2.4123	7.50%	75000	32099								
						Phenol Resin	-----	1.6082	5.00%	50000	21400								
						Bismuth/Bismuth	-----	0.0161	0.05%	500	214								
						SiO2	60676-86-0	27.9665	86.95%	869500	372138								
						C	1333-86-4	0.1608	0.50%	5000	2140								
		Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	0.2534	75.00%	750000	3371										
				epoxy resin curing agent & hardener	Trade secret	0.0676	20.00%	200000	899										
		Tin solder	Pure Tin	Sn	7440-31-5	1.6994	100.00%	1000000	22614										

Total (mg) 75.151

**Not intentionally added the following material EXCEPT AS NOTED ABOVE**

1. Cadmium and cadmium compounds
2. Lead and lead compounds
3. Mercury and mercury compounds
4. Hexavalent chromium compounds
5. Polybrominated biphenyls (PBB) and Polybrominated biphenyl ethers (PBDE)
6. Chlorinated organic compounds
7. Organic tin compounds
8. Asbestos
9. Azo compounds
10. diphenylether, pentabromo derivative C12H5Br5O
11. diphenylether, octabromo derivative C12H2Br8O

RoHS COMPLIANCE STATEMENT Compliant with RoHS without exemption application  
RoHS exemption application: None

**MATERIALS DISCLOSURE DISCLAIMER**

1. The materials are disclosed according to JIG-101 "Material Composition Declaration for Electronic Products"
2. Even though all possible efforts have been made to provide you with the most accurate information, we can not guarantee its completeness and accuracy due to the fact that the data has been compiled based on information provided by our subcontractors and raw material suppliers. Complete information may not have been provided to protect their business proprietary information. Based on the above considerations, this information is provided only as estimates of the average weight of these parts and the anticipated significant toxic metals components.
3. These estimates do not include trace levels of dopants and metal materials within the silicon devices contained inside of the finished products.